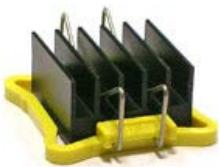


High Performance BGA Cooling Solutions w/ maxiGRIP™ Attachment



| | |
|-------------------------|---|
| ATS Part#: | ATS-53170K-C1-R0 |
| Description: | maxiGRIP™ HS Assembly-SF-LP, T766, BLACK-ANODIZED |
| Heat Sink Type: | Straight Fin |
| Heat Sink Attachment: | maxiGRIP |
| Equivalent Part Number: | ATS-53170K-C2-R0 Discontinued |

*Image above is for illustration purpose only.

Features & Benefits

- High aspect ratio, straight fin heat sinks that are ideal for compact PCB environments
- maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB
- Designed specifically for BGAs and other surface mount packages
- Meets Telcordia GR-63-Core Office Vibration; ETSI 300 019 Transportation Vibration; and MIL-STD-810 Shock Testing and Unpackaged Drop Testing standards
- Comes pre-assembled with high performance, phase changing, thermal interface material
- Designed for low profile components from 1.5 to 2.99mm
- "Keep-Out" Requirements: An "Un-Populated" border zone of 5mm around the component is necessary to facilitate the Installation/Removal of the maxiGRIP™. Please refer to the [maxiGRIP™ Keep-Out Guidelines](#) and [maxiGRIP™ Installation/Removal Instructions](#) for further details.

Thermal Performance

| AIR VELOCITY | | @200 LFM 1.0 M/S | @300 LFM 1.5 M/S | @400 LFM 2.0 M/S | @500 LFM 2.5 M/S | @600 LFM 3.0 M/S | @700 LFM 3.5 M/S | @800 LFM 4.0 M/S |
|--------------------|---------------|---------------------|---------------------|---------------------|---------------------|---------------------|---------------------|---------------------|
| THERMAL RESISTANCE | Unducted Flow | 13.10 °C/W | 10.43 °C/W | 9.02 °C/W | 8.09 °C/W | 7.41 °C/W | 6.90 °C/W | 6.48 °C/W |
| | Ducted Flow | 7.80 | n/a | n/a | n/a | n/a | n/a | n/a |

Product Detail

| Schematic Image | Dimension A | Dimension B | Dimension C | Dimension D | TIM | Finish |
|---|-------------|-------------|-------------|-------------|------|----------------|
| | 17.0 mm | 17.0 mm | 14.5 mm | mm | T766 | BLACK-ANODIZED |
| Notes: | | | | | | |
| <ul style="list-style-type: none">Dimension A and B refer to component size.Dimension C is the heat sink height from the bottom of the base to the top of the fin field.ATS-53170K-C2-R0 is the exact heat sink assembly with an equivalent thermal interface material (Saint Gobain C1100F). NOTE: Saint Gobain C1100F is discontinued effective 12/31/10.Thermal performance data are provided for reference only. Actual performance may vary by application.ATS reserves the right to update or change its products without notice to improve the design or performance.ATS certifies that this heat sink assembly is RoHS-6 and REACH compliant.Optional maxiGRIP™ Installation/Removal Tool Set P/N: MGT170Contact ATS to learn about custom options available. | | | | | | |

*Image above is for illustration purpose only.

For more information, to find a distributor or to place an order, please contact us at 781-769-2800 (North America), sales@qats.com or www.qats.com.

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